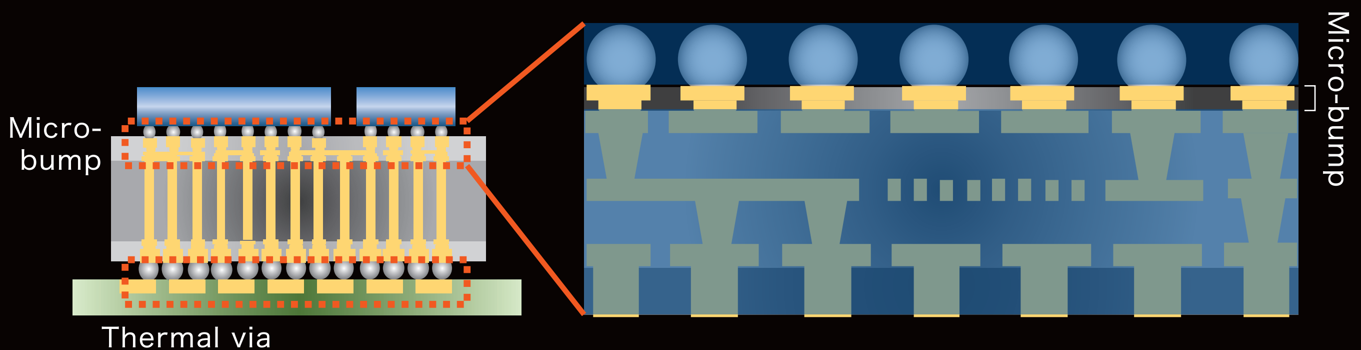
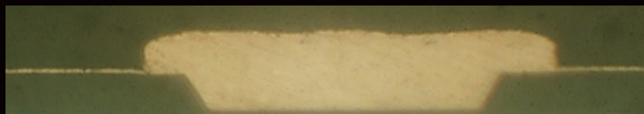
Acid copper plating additive to low aspect via filling for high current, high heat radiation

TORYZA LCN SD

- Can use for low aspect ratio vias to make micro bumps
- Can use for thermal vias to realize low noise, high current density, heat radiation
- Can use also for trench filling

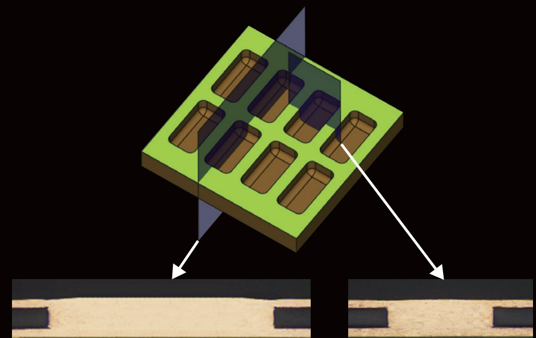


Micro-bump formation



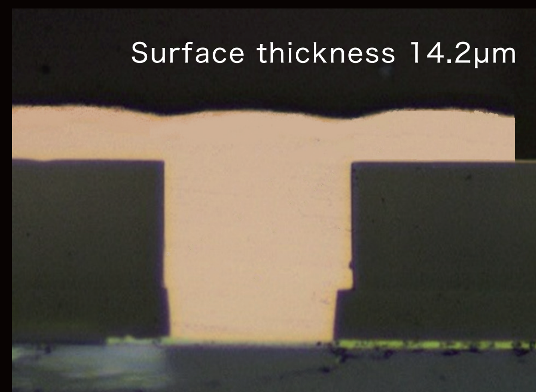
Current density 1.5A/dm², 15min, via diameter 40μm, via depth 5μm

Thermal via filling



50×100μm, via depth 30μm
Current density 1.5A/dm², Plating time 60min

Trench filling



Current density 1.5A/dm², 60min, trench width 50μm, depth 55μm